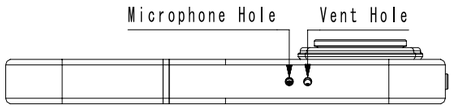
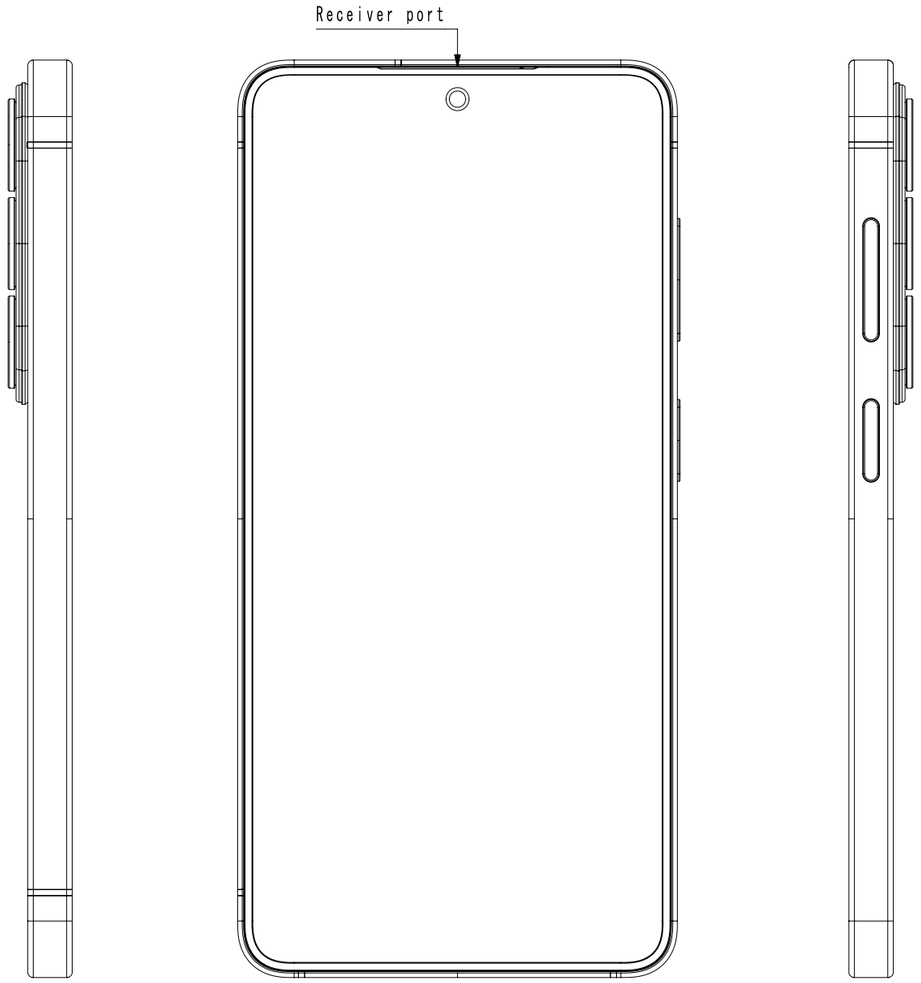
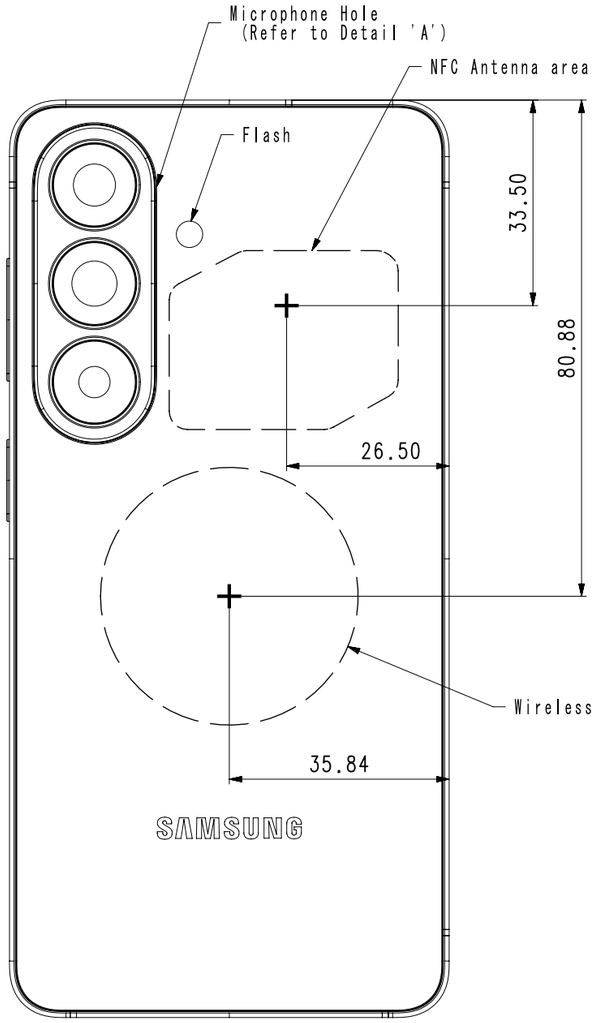
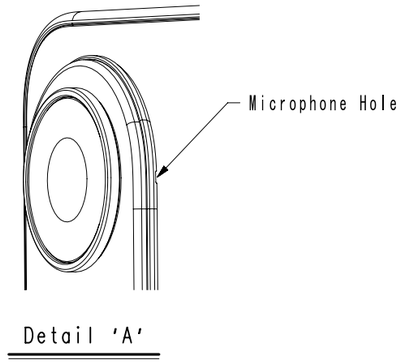
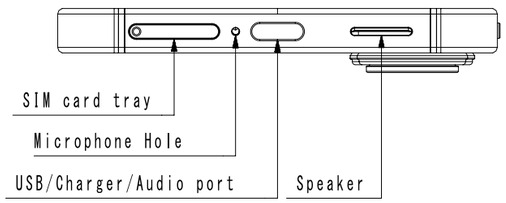






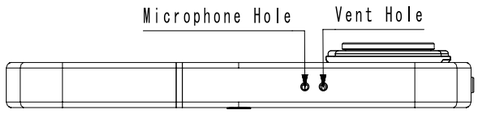


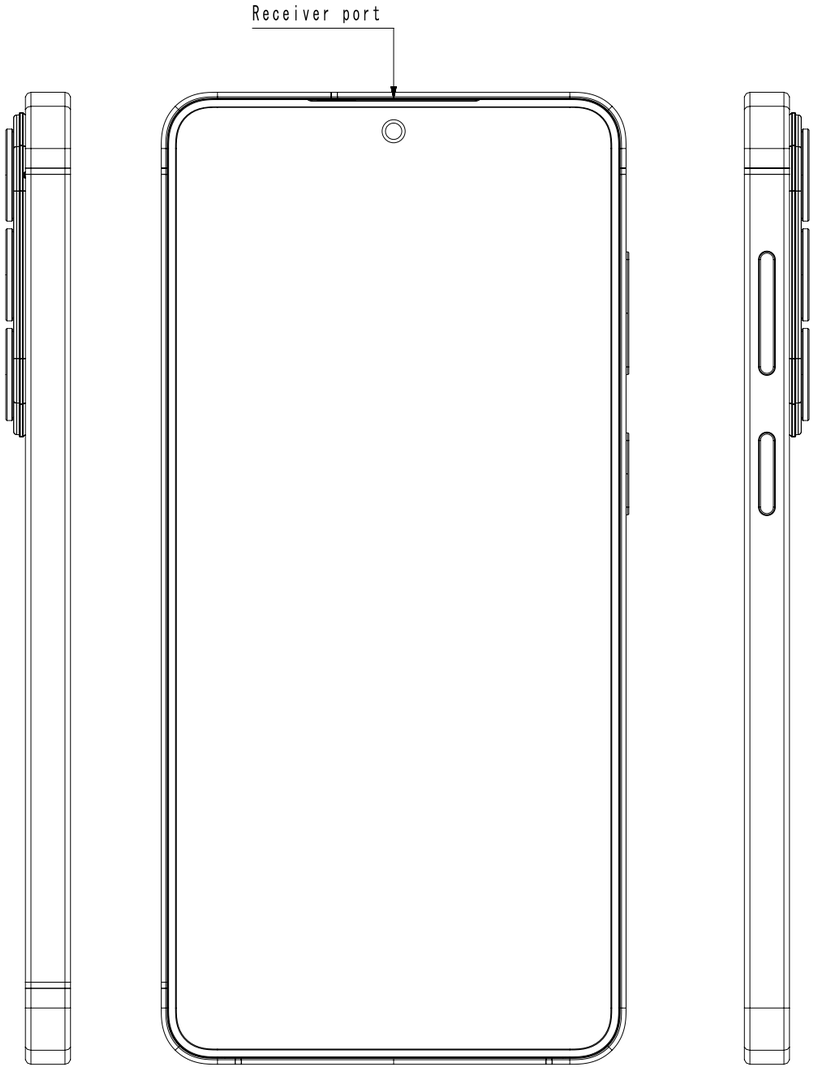


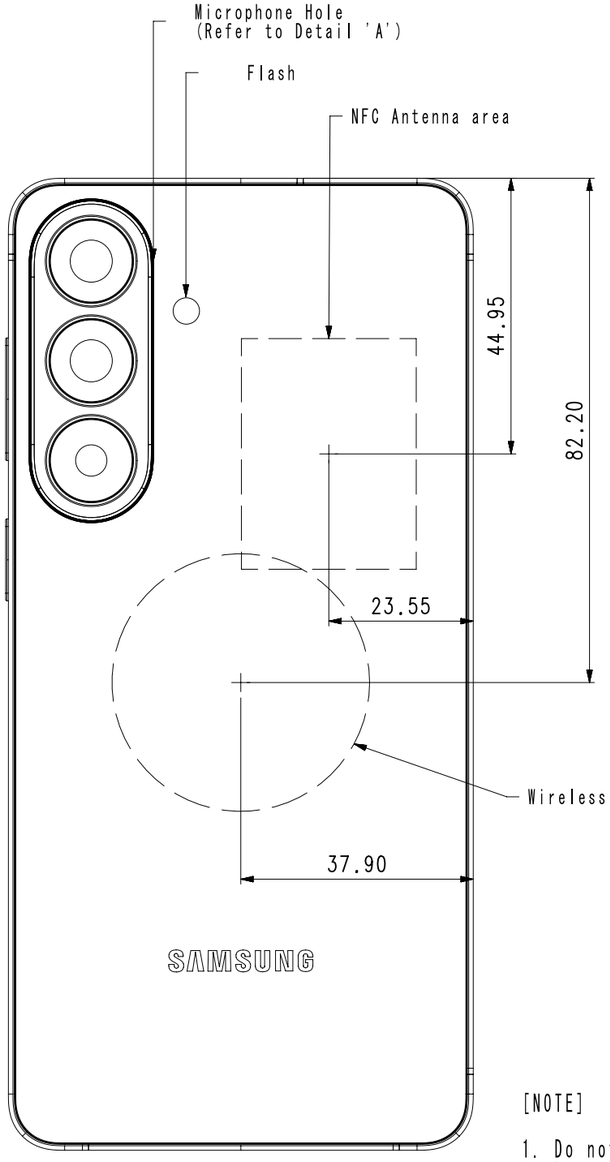
[NOTE]

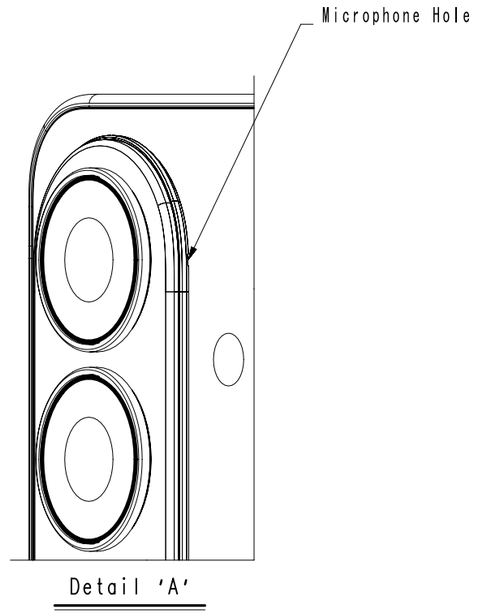
1. Do not block ports (USB/Charger/Audio port)
2. Do not block holes (Microphone, Speaker, Vent)
3. Do not block the image features (Camera, Flash)
4. Do not obstruct NFC Antenna and wireless charging coil area with metal or other conductive material

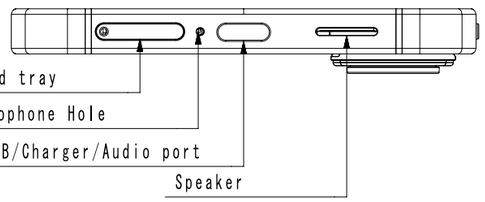
Projection: 3rd ANGLE	SAMSUNG	Scale: None; Size S; Unit: mm; Sheet No.: 1/1	Model: Galaxy S26











[NOTE]

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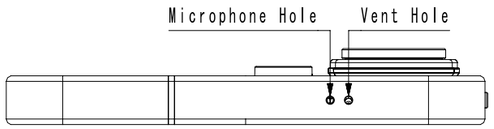
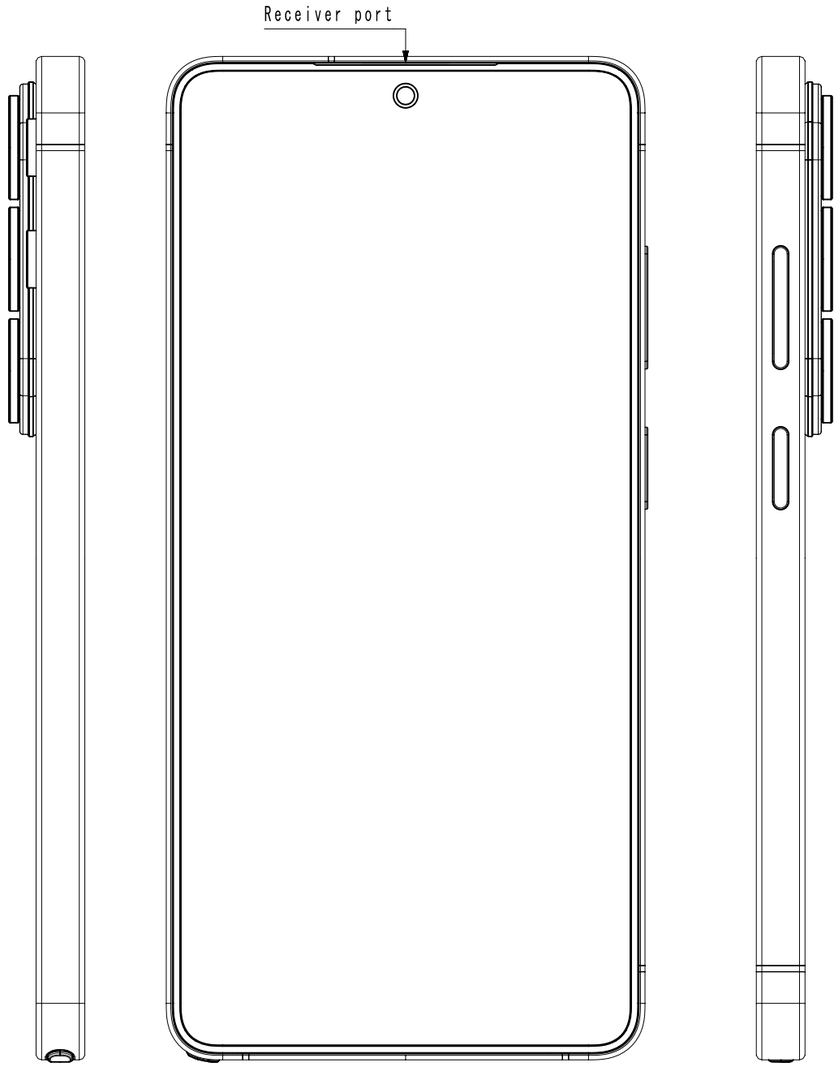
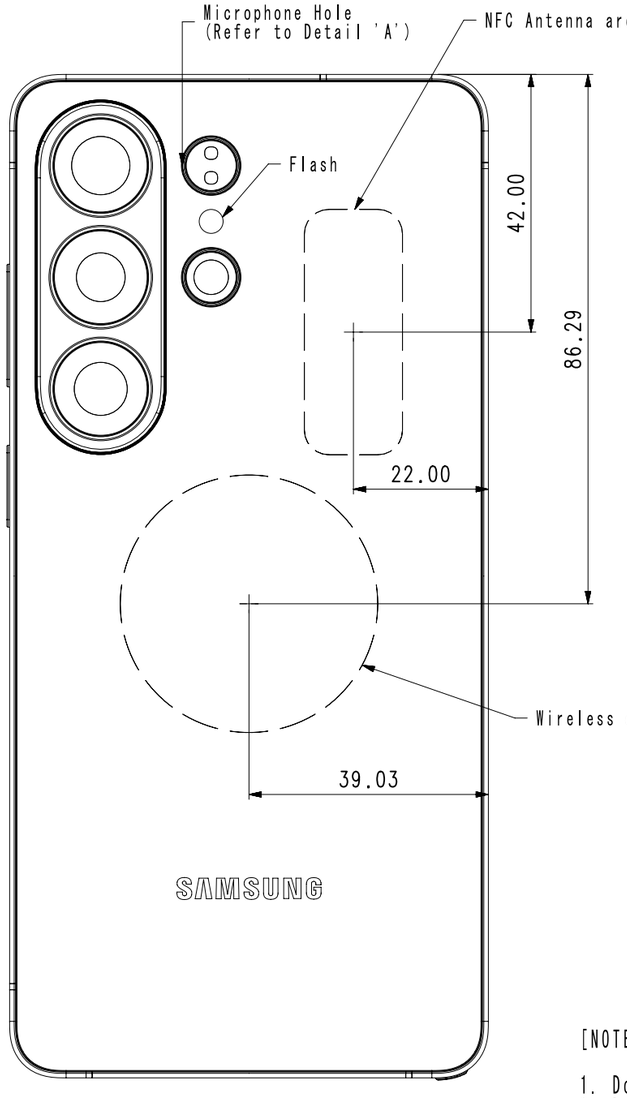
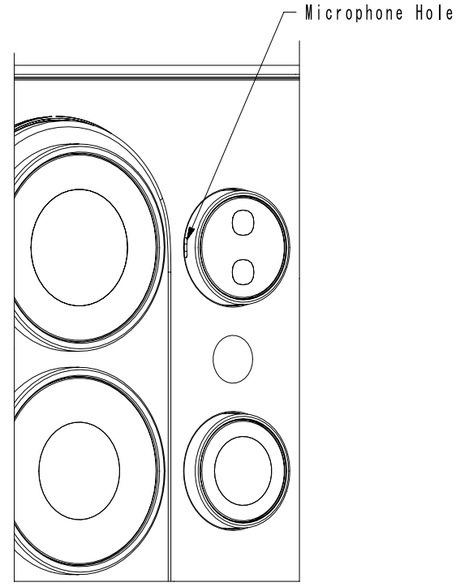
Projection: 3rd ANGLE	SAMSUNG	Scale: None; Size S; Unit: mm; Sheet No.: 1/1	Model: Galaxy S26 Plus

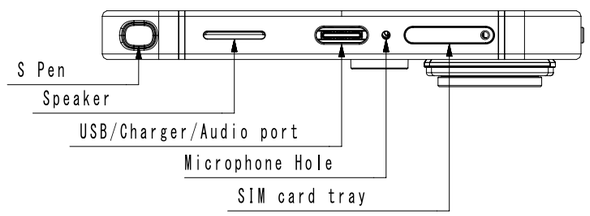








Detail 'A'



[NOTE]

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Projection: 3rd ANGLE	SAMSUNG	Scale: None; Size S; Unit: mm; Sheet No.: 1/1	Model: Galaxy S26 Ultra

S26 Series reference design guide : Magnet Position & Cover Thickness

□ MPP Cover Guide #1

① Magnet Position

- There is an offset between the magnet center and the device center

② Cover Thickness ($d_{z,1}$: 1.5T ~ 1.9T)

($d_{z,1}$= $d_{z,2}$+d_m+$d_{z,3}$+$d_{z,air}$)

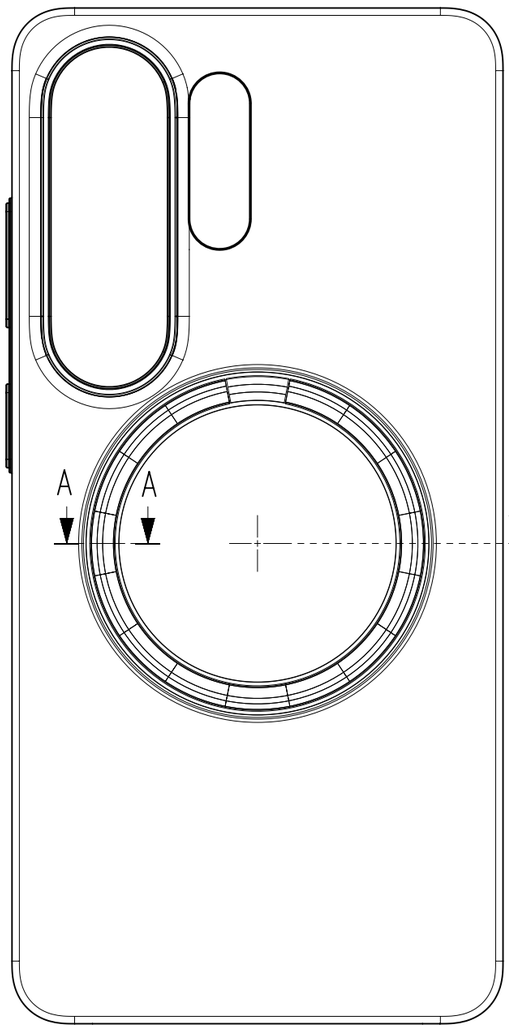
- S26 Series devices are designed for Qi2 standard within the 1.5T ~ 1.9T range.
- $d_{z,1}$ includes the air gap between the device and cover.
- The sum of $d_{z,air}$ and $d_{z,3}$ shall be 0.35T, and adjustable within this range.

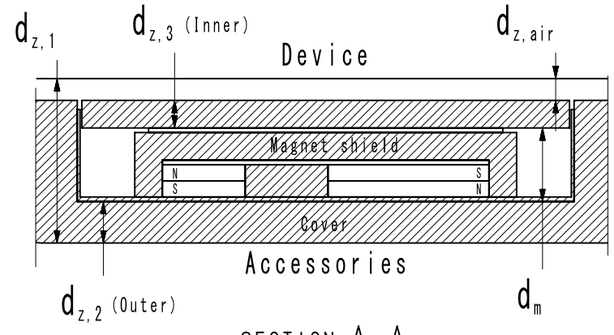
③ Thickness of Magnet ↔ Cover Surface ($d_{z,2}$: 0.4T ~ 0.8T)

- Design required within 0.4T to 0.8T to maintain ideal magnetic coupling with accessories.
- Maximum 0.8T to be maintained to control pull force / shear force.

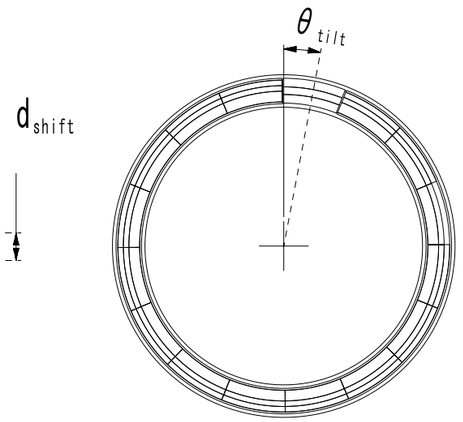
④ Tilt Angle of 'A' Magnet (θ_{tilt})

- 'A' magnet is located between SPCC slit; see 'Magnet Characteristics' page for details.
- θ_{tilt} may vary depending on the hall IC position of each model.





SECTION A-A



□ Key Dimension

	S26 Ultra	S26 Plus	S26
θ_{tilt} (Tol ±1°)	0°	←	←
d_{shift}	4.5mm	3mm	6.1mm
$d_{z,1}$	1.5~1.9mm	←	←
$d_{z,2}$	0.4 ~ 0.8mm (Max 0.8mm, minus tol. only)	←	←
$d_{z,3}$+$d_{z,air}$	0.35mm	←	←

※ Tolerance : ±0.05mm, unless otherwise specified

Projection: 3rd ANGLE	SAMSUNG	Scale: None; Size S; Unit: mm; Sheet No.: 1/1	Model: Galaxy S26 Series

S26 Series reference design guide : Magnet Characteristics

□ MPP Cover Guide #2

① 'A' Magnet is designed to prevent bridging in SPCC slit
: Expoxy Coating & $\theta_{A,m}$ (21.5°)

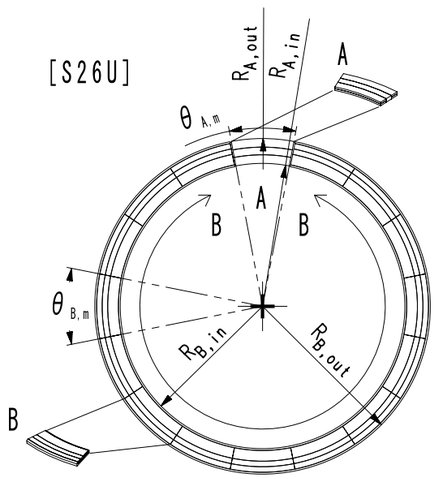
② Magnetized zone : Magnetized zone of 'B' Magnet is asymmetric

③ 'A' and 'B' Magnet have different thicknesses
: $T_{m,A}$ (0.7T), $T_{m,B}$ (0.35T)

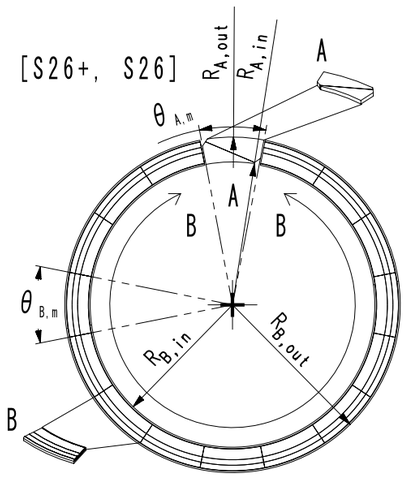
④ Magnet Shield Thickness and Material : T_S (0.3T), SPCC (EGI)

⑤ Total Thickness : T_{tt} (0.75T) includes adshesive applied to the cover

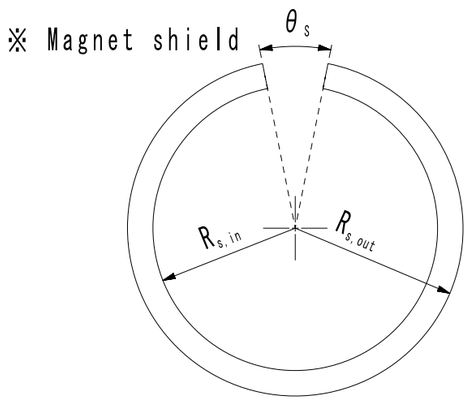
[S26U]



[S26+, S26]



※ Magnet shield

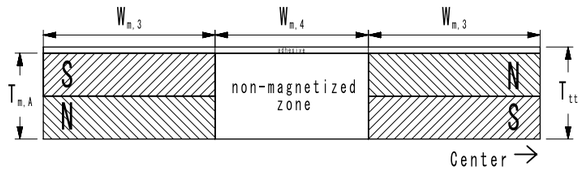


□ Key Dimension (Magnet Shield)

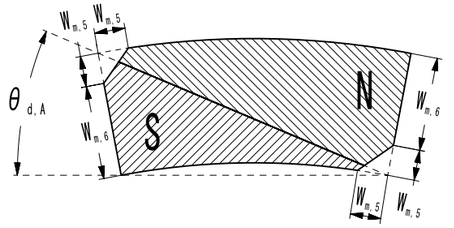
Material	SPCC (EGI)
θ_S	22.5°
$R_{s,in}$	23.2 mm
$R_{s,out}$	27.35 mm
Magnet Shield Width ($R_{s,out}$-$R_{s,in}$)	4.15 mm
T_s	0.3 mm

※ 'A' Magnet Magnetization Pattern

ⓐ S26U (Side View)

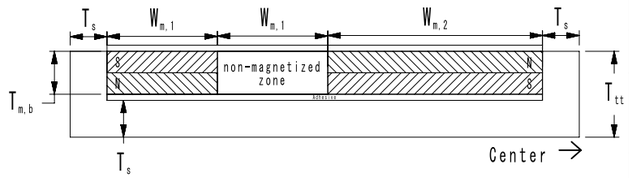


ⓑ S26+, S26 (TOP View)



**Careful attention to the direction of insertion is required

※ 'B' Magnet Magnetization Pattern



□ Key Dimension (Magnet)

Magnet Grade (Surface Finish)	A : N35SH (Epoxy) B : N45SH (Ni)
$\theta_{A,m}$ / $\theta_{B,m}$	A : 21.5° / B : 22.5°
$R_{A,in}$ / $R_{A,out}$	23.3 / 27.35 mm
$R_{B,in}$ / $R_{B,out}$	23.5 / 27.05 mm
$W_{m,1}$	0.9 mm
$W_{m,2}$	1.75 mm
$W_{m,3}$	1.4 mm
$W_{m,4}$	1.25 mm
$W_{m,5}$	1.00 mm
$W_{m,6}$	3.05 mm
$\theta_{d,A}$	22.5°
Magnet Width	A : 4.05mm B : 3.55mm
T_{adh} (magnet ↔ cover) T_{adh} (magnet ↔ SPCC)	0.05 mm
$T_{m,A}$	0.7 mm
$T_{m,B}$	0.35 mm
T_{tt}	0.75 mm

※ Tolerance : ±0.05mm, unless otherwise specified

Projection: 3rd ANGLE	SAMSUNG	Scale: None Size S Unit: mm Sheet No.: 1/1	Model: Galaxy S26 Series